



PATENT
8040-1036

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Masamoto TAGO et al.

Confirmation No. 7977

Serial No. 10/000,020

GROUP 2814

Filed December 4, 2001

Examiner Dilinh P. Nguyen

METHOD FOR LAMINATING AND MOUNTING
SEMICONDUCTOR CHIP

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 22, 2004

Sir:

Responsive to the Official Action of November 24, 2003,
please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this
paper.

Amendments to the Claims are reflected in the listing
of claims which begins on page 4 of this paper.

Remarks begin on page 8 of this paper.